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-32-

## CLAIMS

1. A polyimidesiloxane solution composition comprising an organic solvent, a polyimidesiloxane soluble in the organic solvent, at least one curing component selected from the group consisting of an epoxy compound and a polyvalent isocyanate compound, and a silicone defoamer, wherein the silicone defoamer comprises dimethylpolysiloxane, a polysiloxane compound having a hydrophilic group in a side chain thereof or at a terminal thereof, and a micro-powdery silica.

2. The polyimidesiloxane solution composition of claim 1, which comprises 1 to 50 weight parts of the curing component and 1 to 10 weight parts of the silicone defoamer per 100 weight parts of the polyimidesiloxane soluble in the organic solvent.

3. The polyimidesiloxane solution composition of claim 1, in which the defoamer contains the polysiloxane compound having a hydrophilic group in a side chain thereof or at a terminal thereof in an amount larger than an amount of the dimethylpolysiloxane.

4. The polyimidesiloxane solution composition of claim 1, in which the defoamer comprises 1 to 20 weight parts of the micro-powdery silica per total 100 weight parts of the dimethylpolysiloxane and the polysiloxane compound having a hydrophilic group in a side chain thereof or at a terminal thereof.

5. The polyimidesiloxane solution composition of claim 1, in which the hydrophilic group in the side chain or at the terminal of the polysiloxane compound is a polyoxyalkylene group.

6. The polyimidesiloxane solution composition of claim 5, in which the polyoxyalkylene group is a group comprising a copolymer of ethylene oxide and propylene oxide.

5

7. The polyimidesiloxane solution composition of claim 1, which further comprises an inorganic filler.

10 8. The polyimidesiloxane solution composition of claim 1, which further comprises a curing catalyst.

9. The polyimidesiloxane solution composition of claim 1, in which the silicone defoamer shows a water drop contact angle of not higher than 50°.

15

10. A method of preparing a wiring board having an insulating cured film on a surface thereof, which comprises a step of coating the polyimidesiloxane solution composition of claim 1 on a local area of an electric circuit surface of a wiring board to form a coated film, and a step of heating the coated film to give an insulating cured film.

11. A method of connecting an electronic component to a wiring board, which comprises the steps of coating the polyimidesiloxane solution composition of claim 1 on a local area of an electric circuit surface of a wiring board to form a coated film, heating the coated film to give an insulating cured film, and connecting an electronic component via an anisotropic conductive material to a wiring surface of the wiring board in an area having no insulating cured film thereon.